

Final Product Change Notification

201811009F01

Issue Date: 01-Jan-2019

Effective Date: 15-Apr-2019

Here's your personalized quality information concerning products Digi-Key purchased from Nexperia.
For detailed information we invite you to view this notification online



Change Category

- | | | | | |
|---|--|--|---|---|
| <input checked="" type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input checked="" type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |

Release of 8 inch wafer diameter for general-purpose Schottky diodes

Details of this Change

Release of 8 inch wafer diameter for general-purpose Schottky diodes and Schottky barrier rectifiers. In addition the top side metallization of the affected diodes will be adapted for standarization reasons.

Old products: Production using 6 inch wafer diameter, top side metallization with 1.6µm

Changed products: Production using 6 and 8 inch wafer diameter, top side metallization with 1.5µm (for 8 inch wafer)

Selected types have a change of wire material from Au to Cu with release of 2nd source mold compound and release of lead frame design version SOT323 R1 that have been announced for structurally similar types with precvious PCNs as denoted in attached document.

Production on 8 inch wafer diameter implies the use of the respective 8 inch wafer process technology.

Why do we Implement this Change

To increase flexibility and volume ramp-up.

Identification of Affected Products

The 8 inch products can be identified by a marker on the die surface.

Changed products can be identified by date code after implementation.

Product Availability

Sample Information

Samples are available upon request

Latest sample request date for PCN samples is 31-Jan-2019.

Production

Planned first shipment 01-May-2019

Impact

No impact to the products' functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted.

Supply using 6 inch wafer will be continued.

Related Notifications

Notification	Issue Date	Effective Date	Title
201011012F	13-Dec-2010		Change of bond wire material from gold to copper in SOT23 package and 8 inch wafer diameter
201308016F01	14-Dec-2013	14-Mar-2014	Change of bond wire material from Au to Cu and release of 2nd source mold compound
201309012F01	07-May-2014	05-Aug-2014	Change of bond wire from Au to Cu and release of 2nd source mold compound in SOT323
201411005F01	26-Jan-2015	10-May-2015	Change of bond wire from Au to Cu and release of 2nd source mold compound in SOT363
201712005F01	30-Apr-2018	29-Jul-2018	Change of lead frame version in SOT323 package
201807002F01U0103	103-Oct-2018	11-Jan-2019	Release of 8 inch wafer diameter for PMEG4010EPK

Timing and Logistics

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 31-Jan-2019. Lack of acknowledgement of the PCN constitutes acceptance of the change.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact Nexperia "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support team.

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Jonkerbosplein 52 6534 AB Nijmegen, The Netherlands

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Affected Part Numbers

BAS40-04W,115

PMEG4002EJ,115

PMEG4020EPA,115

BAS70-04,215

BAT854CW,115

BAS40L,315

BAT46WJ,115
PMEG6020EPA,115
RB520S30,115
PMEG6010CEJ,115
RB751V40,115
BAS70XY,115
BAS70-07,215
BAS40,215
BAS40-06,215
1PS76SB40,115
BAS40-05,215
1PS70SB44,115
BAS70-06,215
PMEG4010CEJ,115
BAS40,235
BAS40-06W,115
PMEG4002EB,115
1PS79SB30,135
BAS40-07,215
BAT160C,115
PMEG4005CEJX
BAT854CW,135
RB751S40,115
PMEG6010CEH,115
BAT46WH,115
BAS40-05W,115
BAS70H,115
PMEG6010CPA,115
BAS70-06W,115
BAS40-04,215
BAS70-05W,115
BAS40-04,235
PMEG4002EL,315
BAT165AX
1PS70SB45,115
1PS79SB30,115
BAS70-05,215
RB751CS40,315
BAS40H,115
PMEG3010CEH,115
PMEG3010CEJ,115
BAS70L,315
BAT160S,115
BAT854W,115
PMEG4010CEH,115
BAT854SW,115
BAS70-04W,115
PMEG4002ELD,315

BAS70W,115
RB520CS30L,315
BAT160A,115
PMEG6020EPASX
BAS70,215
BAS70-07S,115
1PS79SB40,115
PMEG4010CPA,115
1PS79SB70,115
1PS76SB70,115
1PS76SB70,135
PMEG4010CPASX
PMEG4020EPASX
BAT854AW,115
1PS76SB40,135